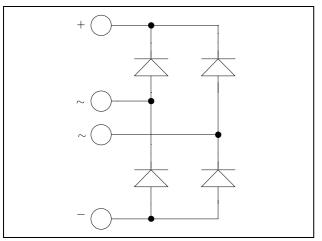
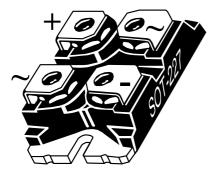


## ISOTOP<sup>®</sup>Fast Diode Full Bridge Power Module

## $V_{RRM} = 600V$ $I_{C} = 60A$ @ Tc = 80°C





### Application

- Switch mode power supplies rectifier
- Induction heating
- Welding equipment
- High speed rectifiers

#### Features

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
- Very low stray inductance
- High level of integration
- ISOTOP<sup>®</sup> Package (SOT-227)

#### Benefits

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant

### Absolute maximum ratings

Symbol	Parameter			Max ratings	Unit	
V <sub>R</sub>	Maximum DC reverse Voltage			600	V	
V <sub>RRM</sub>	Maximum Peak Repetitive Revers	e Voltage			000	v
$I_{F(AV)}$	Maximum Average Forward	Dute and	500/	$T_C = 25^{\circ}C$	90	
	Current	Duty cycle	e - 30%	$T_C = 80^{\circ}C$	60	А
I <sub>FSM</sub>	Non-Repetitive Forward Surge Cu	rrent	8.3ms	$T_J = 45^{\circ}C$	500	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com



## All ratings (a) $T_j = 25^{\circ}C$ unless otherwise specified

## **Electrical Characteristics**

Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit	
$\mathbf{V}_{\mathrm{F}}$	Diode Forward Voltage	$I_F = 60A$	= 60A		1.7	2.3	v
		$I_F = 120A$			2		
		$I_F = 60A$	$T_j = 125^{\circ}C$		1.4		
I <sub>RM</sub>	Maximum Reverse Leakage Current	$V_{R} = 600V$ $T_{i} = 25^{\circ}C$ $T_{j} = 125^{\circ}C$			25		
			$T_{j} = 125^{\circ}C$			500	μA
CT	Junction Capacitance	$V_R = 200V$			145		pF

## **Dynamic Characteristics**

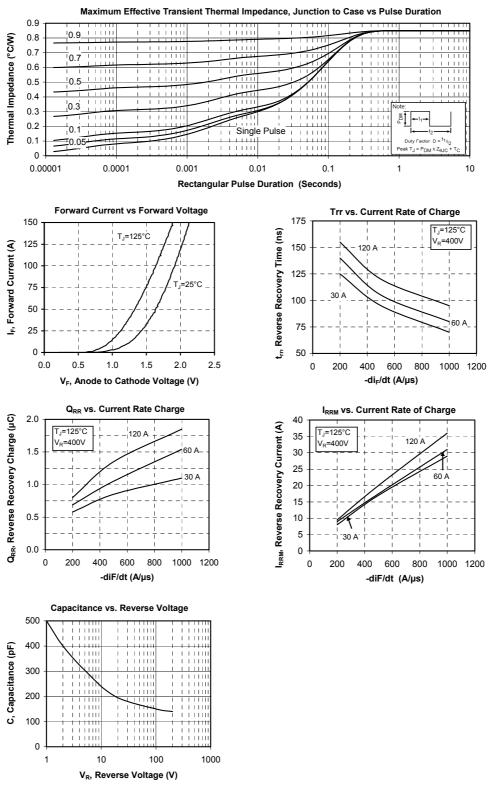
Symbol	Characteristic	Test Conditions		Min	Тур	Max	Unit
t <sub>rr</sub>	Reverse Recovery Time		$T_j = 25^{\circ}C$		70		ns
۲r			$T_{j} = 125^{\circ}C$		140		
Q <sub>rr</sub>	Reverse Recovery Charge	$I_F = 60A$ $V_R = 400V$	$T_j = 25^{\circ}C$		100		nC
Zrr		$di/dt = 200 A/\mu s$	$T_1 = 125^{\circ}C$		690		
I <sub>RRM</sub>	Reverse Recovery Current		$T_j = 25^{\circ}C$		4		Α
IRRM			$T_{j} = 125^{\circ}C$		9		
t <sub>rr</sub>	Reverse Recovery Time	$I_{\rm F} = 60A$ $V_{\rm R} = 400V$ $di/dt = 1000A/\mu s$			80		ns
Qn	Reverse Recovery Charge		$T_j = 125^{\circ}C$		1540		nC
I <sub>RRM</sub>	Reverse Recovery Current				31		А

## Thermal and package characteristics

Symbol	Characteristic	Min	Тур	Max	Unit
R <sub>thJC</sub>	Junction to Case Thermal resistance			0.85	°C/W
R <sub>thJA</sub>	Junction to Ambient			20	C/ W
V <sub>ISOL</sub>	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz	2500			V
$T_{J}, T_{STG}$	Storage Temperature Range	-55		175	°C
T <sub>L</sub>	Max Lead Temp for Soldering:0.063" from case for 10 sec			300	C
Torque	Mounting torque (Mounting = 8-32 or 4mm Machine and terminals = 4mm Machine)			1.5	N.m
Wt	Package Weight		29.2		g



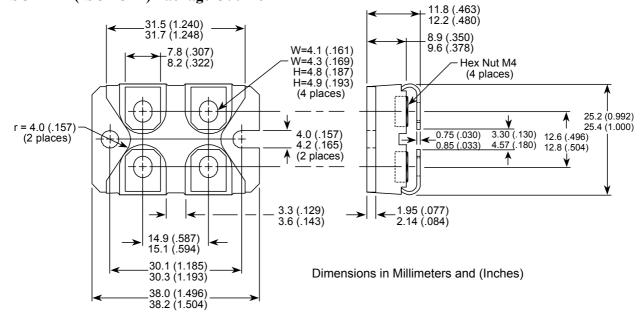
### **Typical Performance Curve**



APT60DF60HJ-Rev 2 October, 2012



### SOT-227 (ISOTOP<sup>®</sup>) Package Outline



ISOTOP® is a registered trademark of ST Microelectronics NV



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